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Applicant(s)
Consuelo N. Tangpuz et al.

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U.S. PATENT DOCUMENTS

[illegible]

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

TH	5	Joshi, R.; Manatad, R.; Tangpuz, C.; FLIP CHIP IN LEADED MOLDED PACKAGE (FLMP); Fairchild Semiconductor; pgs 25-29; 2002.

EXAMINER Te - Te + 10

DATE CONSIDERED

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